

# FDC6332L

## **Common Source Load Switch**

# P-Channel 1.8V Specified PowerTrench® MOSFET

### **General Description**

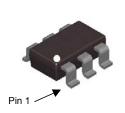
This Load Switch integrates an N-Channel Power MOSFET that drives Common-Source P-Channels and in a small SuperSot^TM-6 package. It uses Fairchild's advanced low voltage PowerTrench process. The  $R_{\text{DS(ON)}}$  is 750  $m\Omega$  per the switch @  $V_{\text{GS}}$  1.8Vand is optimized for battery power management applications.

## **Applications**

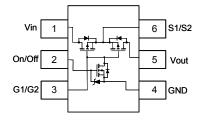
- · Battery management/Charger Application
- · Accessory load switching

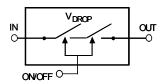
### **Features**

- -1 A, 8 V.  $R_{DS(ON)} = 350 \text{ m}\Omega$  @  $V_{GS} = -4.5 \text{ V}$   $R_{DS(ON)} = 500 \text{ m}\Omega$  @  $V_{GS} = -2.5 \text{ V}$  $R_{DS(ON)} = 750 \text{ m}\Omega$  @  $V_{GS} = -1.8 \text{ V}$
- N-Channel MOSFET includes Zener protection for ESD ruggedness (>6KV Human body model)
- High performance trench technology for extremely low  $R_{\mbox{\scriptsize DS(ON)}}$



SuperSOT™-6





**Equivalent Circuit** 

# Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V <sub>IN</sub>	Input Voltage	±8	V
V <sub>ON</sub>	Turn-On Voltage	8	V
I <sub>Load</sub>	Load Current - Continuous (Note 1)	-1.0	Α
	- Pulsed	-2.0	
P <sub>D</sub>	Maximum Power Dissipation (Note 1)	0.7	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

## **Thermal Characteristics**

R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	(Note 1)	160	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	90	

# **Package Marking and Ordering Information**

	Device	Reel Size	Tape width	Quantity
.332	FDC6332L	7"	8mm	3000 units

### **Electrical Characteristics** T<sub>A</sub> = 25°C unless otherwise noted **Units Symbol Parameter** Min **Test Conditions** Typ Max **Off Characteristics** Input - Output Breakdown Voltage $I_D = -250 \, \mu A$ -20 ٧ $BV_{IN}$ $V_{ON/OFF} = 0 V$ $IR_{IN}$ $V_{IN} = -8V$ Reverse Input Current $V_{ON/OFF} = 0 V$ -1 μΑ $\mathsf{BVG}_{\mathsf{OFF}}$ Driver FET Gate Breakdown Voltage $I_G = 250uA$ 8 V $V_G = 8 V$ 100 Driver FET Gate Leakage Current nΑ $I_{GOFF}$ **On Characteristics** (Note 2) Input Voltage Range 1.8 2.5 ٧ $V_{IN}$ ٧ $V_{ON}$ Turn-On Voltage Range 1.5 8 -0.2 ٧ Turn-off Voltage Range 0.2 $V_{OFF}$ **Output Load Current** $V_{IN} = -5 V$ $V_{ON} = -4.5V$ -1 Α $\mathsf{I}_{\mathsf{LOAD}}$ $R_{DS(on)}$ Static Drain-Source $V_{GS} = 4.5 \overline{V}$ $I_D = -1.0A$ 230 350 $\mathsf{m}\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings** 

Is	Maximum Continuous Drain–Source Diode Forward Current			-0.6	Α
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{ON/OFF} = 0 \text{ V}, I_S = -0.6 \text{ A} \text{ (Note 2)}$	-0.9	-1.2	V

 $V_{GS} = 2.5 V$  $V_{GS} = 1.8 V,$ 

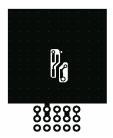
 $V_{IN} = 8 V$ ,

 $V_{IN} = 8 V$ 

 $V_{IN} = 8 V$ 

 $R_{\text{ON}}$ 

1. R<sub>0JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



90°C/W when mounted on a 1in2 pad of 2 oz copper



 $I_D = -0.9 A$ 

 $I_D = -0.7 A$ 

 $I_D = -1.0 A$ 

 $I_D = -0.9 A$ 

 $I_D = -0.7 A$ 

160°C/W when mounted on a minimum pad of 2 oz

338

643

409

411

420

500

750

 $\text{m}\Omega$ 

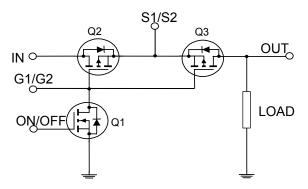
Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width <  $300\mu$ s, Duty Cycle < 2.0%

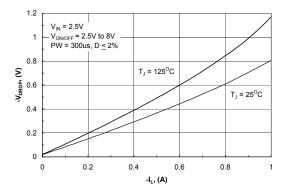
On-Resistance

Loadswitch On-Resistance

## FDC6332L Load Switch Application Circuit



# **Typical Characteristics**



V<sub>IN</sub> = 3.3V 8.0 V<sub>ON/OFF</sub> = 2.5V to 8V PW = 300us, D ≤ 2% € 0.6 T<sub>J</sub> = 125<sup>O</sup>C -**P** 0.4 T<sub>J</sub> = 25<sup>O</sup>C 0.2 0 0.2 0.4 0.6 8.0 0 -I<sub>L</sub>, (A)

Figure 1. Conduction Voltage Drop Variation with Load Current.

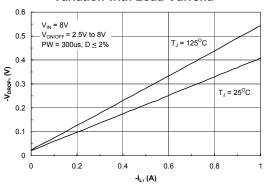


Figure 2. Conduction Voltage Drop Variation with Load Current.

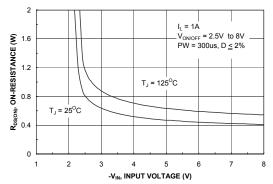


Figure 3. Conduction Voltage Drop Variation with Load Current.



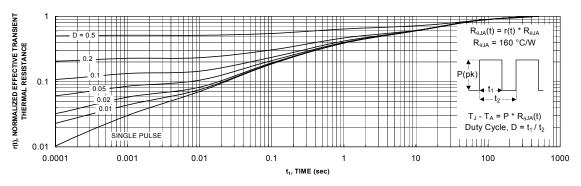


Figure 5. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1 Transient thermal response will change depending on the circuit board design.

### **TRADEMARKS**

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FACT™	ImpliedDisconnect™	PACMAN™	SPM™
ActiveArray™	FACT Quiet Series™	ISOPLANAR™	POP™	Stealth™
Bottomless™	FAST®	LittleFET™	Power247™	SuperSOT™-3
CoolFET™	FASTr™	MicroFET™	PowerTrench®	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	QS™	SyncFET™
EcoSPARK™	GTO™ .	MSX™	QT Optoelectronics™	TinyLogic <sup>®</sup>
E <sup>2</sup> CMOS <sup>TM</sup>	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I <sup>2</sup> C <sup>TM</sup>	OCX™	RapidConfigure™	UHC™
Across the board.	Around the world.™	OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franch	nise™	OPTOLOGIC®	SILENT SWITCHER®	VCX™
Programmable Ac	tive Droop™	OPTOPLANAR™	SMART START™	

### **DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

### PRODUCT STATUS DEFINITIONS

### **Definition of Terms**

Datasheet Identification	Product Status	Definition		
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.		
Preliminary First Production		This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.		
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.		
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.		